

CIR-W3SUSPS1304G****

DDR3 WIDE TEMP. SO-DIMM 1333MHz 4GB

Description

The CIR-W3SUSPS1304G is 512M words X 64 bits, 1 rank. Unbuffered Small Outline Dual In-Line Memory Module (SO-DIMM). DDR3 SDRAMs in Fine Ball Grid Array(FBGA) packages on a 204pin glass-epoxy substrate. Provide a high performance 8 byte interface in 67.60mm width form factor of industry standard. It is suitable for easy interchange and addition.

Specifications

Density	4GB
Pin Count	204pin
Type	Unbuffered
Dimensions	67.6mm x 30.0mm
ECC	Non-ECC
Component Config	512M x 8 bit
Data Rate	1333 MHz
CAS Latency	9
Voltage	1.35V / 1.5V
PCB Layers	8
Operating Temp.(TCASE)	-40°C~+85°C
Module Ranks	Single Rank

Features

- 204pin, Small outline dual in-line memory module(SO-DIMM)
- Power supply: VDD= 1.35V (1.28V to 1.45V) & VDD= 1.5V (1.425V to 1.575V)
- Interface: SSTL_15
- CAS (READ) latency (CL): 6, 7, 8, 9
- POSTED CAS ADDITIVE latency (AL)
- Fully differential clock inputs (CK, /CK) operation
- Differential Data Strobe (DQS, /DQS)
- DM masks write data-in at the both rising and falling edges of the data strobe
- BL switch on the fly
- 8banks
- 8K refresh cycles /64ms
- Dynamic On Die Termination supported
- Asynchronous RESET pin supported
- ZQ calibration supported
- TDQS (Termination Data Strobe) supported (x8 only)
- Write Levelization supported
- Refresh: Auto-Refresh, Self-Refresh
- 8 bit pre-fetch
- Lead-Free Products are RoHS compliant
- Support Industrial Temp (-40 ~85°C)
- tREFI 7.8us at -40 °C ≤ TCASE ≤ 85°C

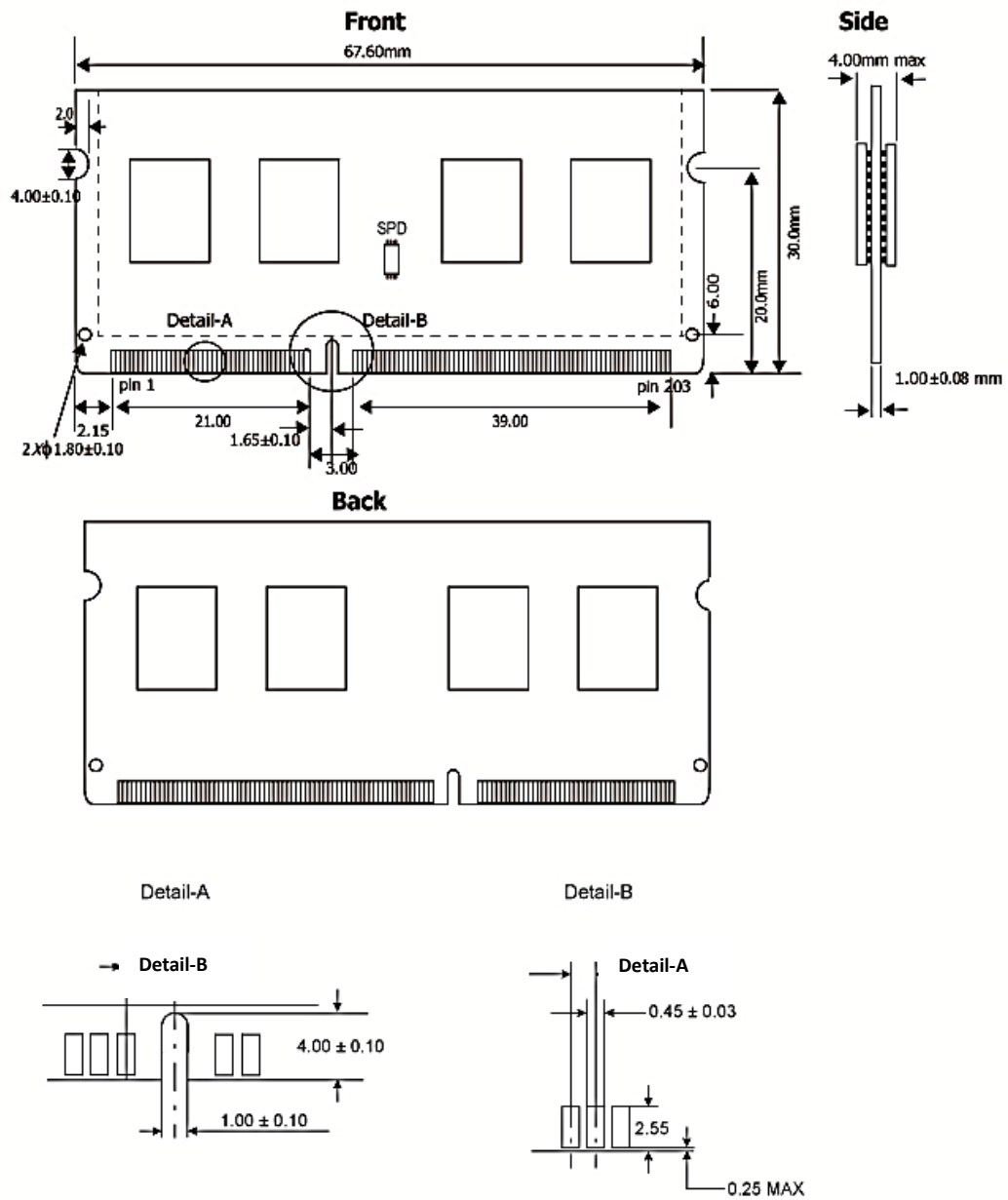


Speed Grade

Frequency Grade	Data Transfer Rate	CAS Latency Support				CL-tRCD-tRP
		CL6	CL7	CL8	CL9	
DDR3-1333	PC3-10600	800	1066	1066	1333	9-9-9

Package Dimensions

Unit: mm



Tolerances : ± 0.15mm unless otherwise specified